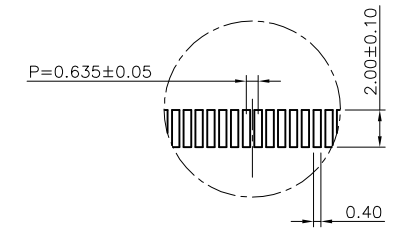
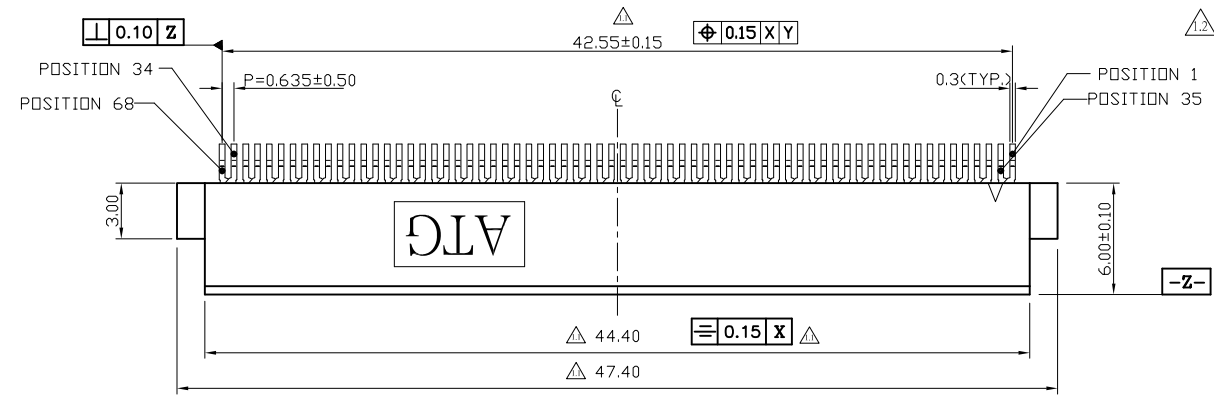


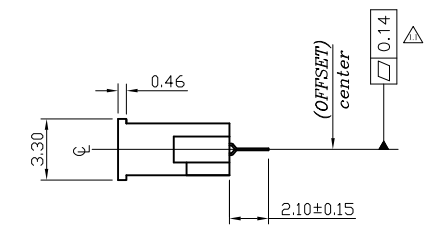
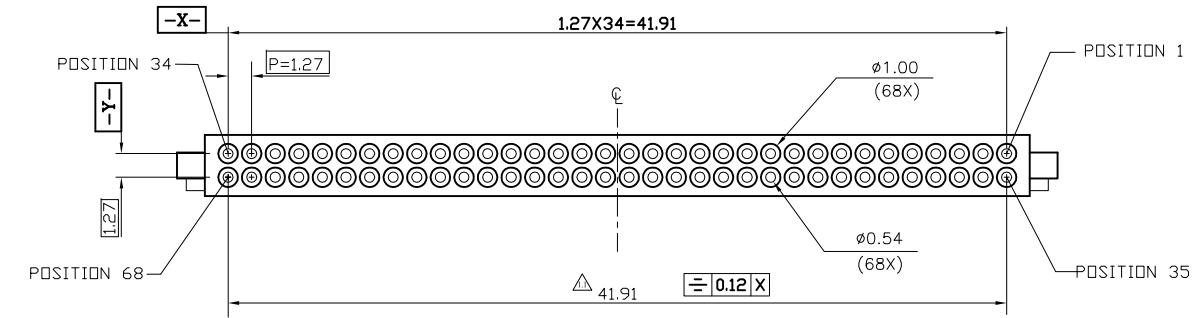
REV.	MARK	ECN NO.	MODIFY DES.	DR.	DATE
1.0				PENNY	02/05/02
1.1	△	ECN03082901	修改公差尺寸	N.L.SU	08/29/03
1.2	△	ECN03111201	增加無鉛料號	FANG	11/12/03

NOTES:

- MATERIAL:**
HOUSING: L.C.P. ,GLASS FILLED.
CONTACT: COPPER ALLOY.
- PLATING:** GOLD PLATING IN CONTACT AREA,
120u" PLEASE SEE TABLE I FOR PLATING
COMPONENTS, 90/10 IN TAIL ZONE,
OVER 50u" NICKEL UNDERPLATING
OVER ALL.



PCB LAYOUT



△ TABLE I

PART NO.	PACKING	TIN/LEAD ALLOY RATE
139640-80ATG220	TAPE ON REEL	100/0
139640-80ATG120	TUBE	100/0
139640-40ATG220	TAPE ON REEL	90/10
139640-40ATG120	TUBE	90/10

DWG NO. 13908-ATG130		ATERGI TECHNOLOGY LTD.,			
P/N SEE TABLE I		APPD: 張春龍	TITLE: 68P Conn. SMT 無導柱 (OFFSET 0.0)		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS TOLERANCES		CHKD: 蘇正龍			
		DR: 林美芳	SCALE: 5 : 1	UNITS: MM	
		REV. 1.2	SHEET: 1 OF 1	DATE: 02.05.2002	